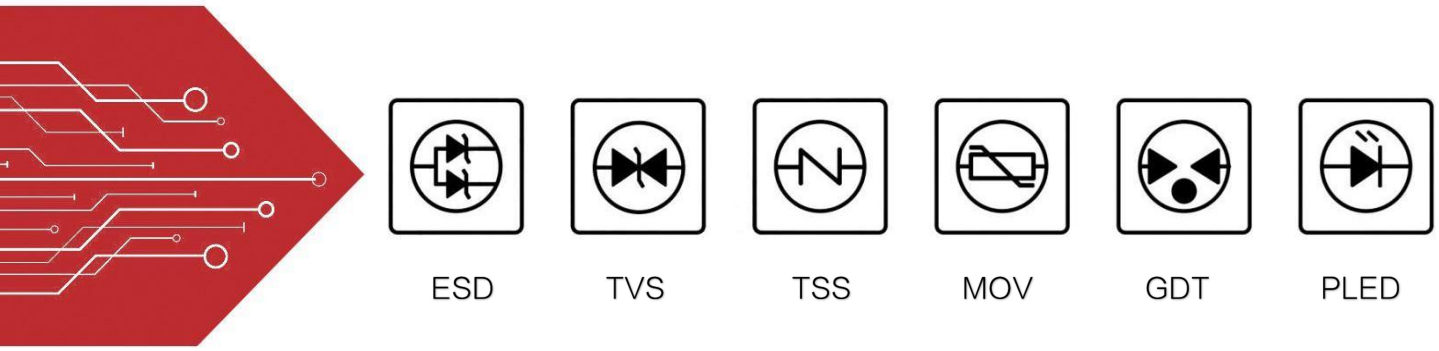
MSKSEMI
SEMICONDUCTOR



Product data sheet

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FEATURES

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Low reverse leakage
- Built-in strain relief,ideal for automated placement
- High forward surge current capability
- High temperature soldering guaranteed: 250ºC/10 seconds at terminals

MECHANICAL DATA

Case: JEDEC DO-214AC molded plastic body
Terminals: Solder plated, solderable per MIL-STD-750, Method 2026
Polarity: Color band denotes cathode end
Mounting Position: Any
Weight:0.002 ounce, 0.07 grams

MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings at 25ºC ambient temperature unless otherwise specified.
Single phase half-wave 60Hz,resistive or inductive load,for capacitive load current derate by 20%.

	SYMBOLS	M1	M2	M3	M4	M5	M6	M7	UNITS
Maximum repetitive peak reverse voltage	V_{RRM}	50	100	200	400	600	800	1000	VOLTS
Maximum RMS voltage	V_{RMS}	35	70	140	280	420	560	700	VOLTS
Maximum DC blocking voltage	V_{DC}	50	100	200	400	600	800	1000	VOLTS
Maximum average forward rectified current at T_L=75ºC	$I_{(AV)}$	1.0							Amp
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30.0							Amps
Maximum instantaneous forward voltage at 1.0A	V_F	1.1							Volts
Maximum DC reverse current T_A=25ºC at rated DC blocking voltage T_A=100ºC	I_R	5.0 50.0							μA
Typical junction capacitance (NOTE 1)	C_J	15.0							pF
Typical thermal resistance (NOTE 2)	$R_{\theta JA}$	75.0							°C/W
Operating junction and storage temperature range	T_J,T_{STG}	-65 to +150							°C

Note:1.Measured at 1MHz and applied reverse voltage of 4.0V D.C.
2.P.C.B. mounted with 0.2x0.2"(5.0x5.0mm) copper pad areas

FIG. 1- FORWARD CURRENT DERATING CURVE

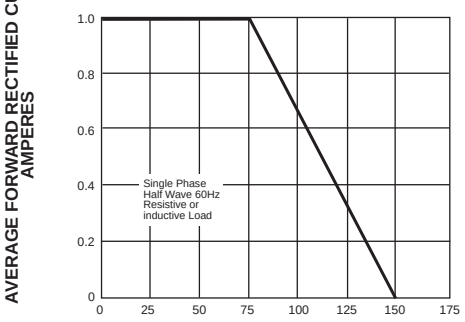


FIG. 2-MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

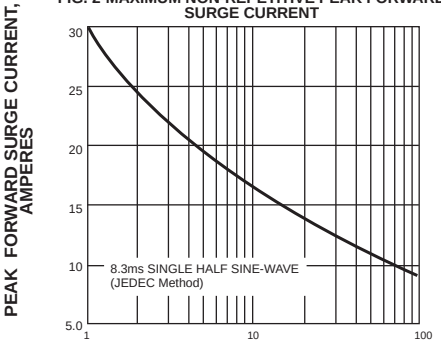


FIG. 3-TYPICAL INSTANTANEOUS FORWARD CHARACTERISTICS

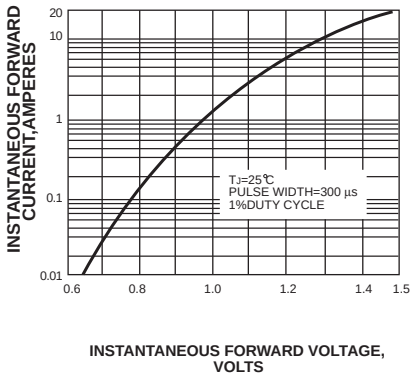


FIG. 4-TYPICAL REVERSE CHARACTERISTICS

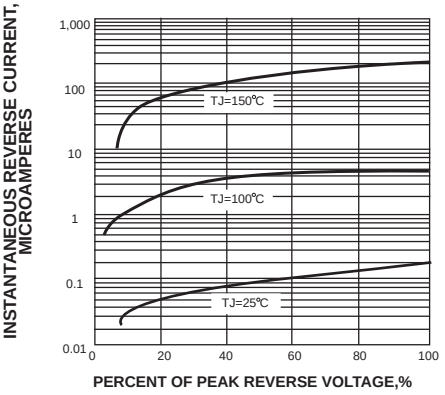


FIG. 5-TYPICAL JUNCTION CAPACITANCE

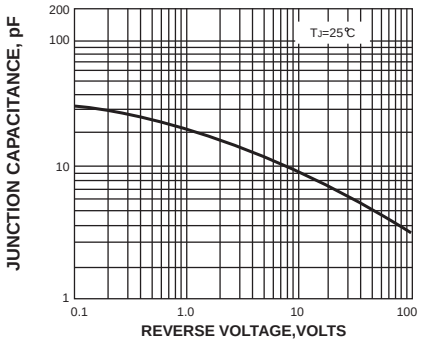
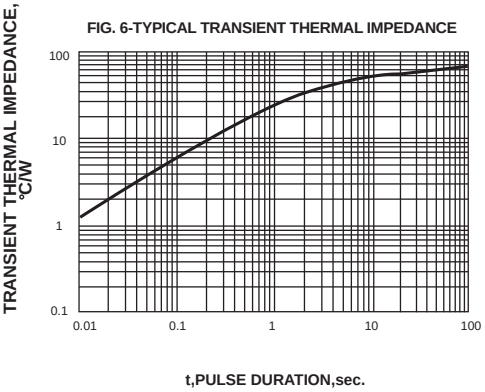
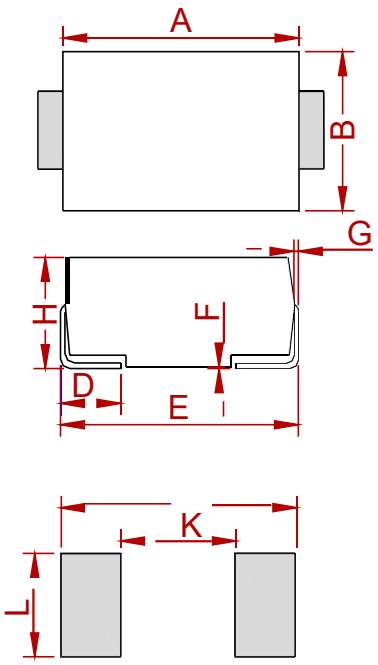


FIG. 6-TYPICAL TRANSIENT THERMAL IMPEDANCE



PACKAGE MECHANICAL DATA



DO-214AC (SMA)

Ref.	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.25	4.65	0.167	0.183
B	2.50	2.90	0.098	0.114
C	1.35	1.65	0.053	0.065
D	0.76	1.52	0.030	0.060
E	4.93	5.28	0.194	0.208
F	0.051	0.203	0.002	0.008
G	0.15	0.31	0.006	0.012
H	1.98	2.41	0.078	0.095
J	6.50		0.256	
K		2.30		0.090
L	1.70		0.067	

REEL SPECIFICATION

P/N	PKG	QTY
M1 THRU M7	SMA	2000

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